

# FORMIKE ELECTRONIC CO.,LTD

# PRDUCT SPECIFICATON

# TFT LCD MODULE

# MODEL : KWH022A02-F02

- [ ] Preliminary Specification
  - [ ] Finally Specification

CUSTOMER'S APPROVAL				
SIGNATURE:	DATE:			

APPROVED	PM	PD	PREPARED
BY	REVIEWD	REVIEWD	BY
Wayne	Li tong	Zhengjinrong	Jully

Prepared By :

FORMIKE ELECTRONIC CO., LTD

Address : A909, Huaying Building, 97 Nanshang Road, Nanshan District, Shenzhen, China.518054 TEL:(86) 755 88306921,88306931 FAX:(86) 755 88304615 Http:// www.wandisplay.com

• This specification is subject to change withouth notice.Please contact FORMIKE or it's representative before designing your product based on this specification.

Issued Date: Feb-28-2008



#### **REVISION RECORD**

REV NO.	REV DATE	CONTENTS	REMARKS
0.1	2008-02-28	First release	



# CONTENTS

- GENERAL INFORMATION
- ABSOLUTE MAXIMUM RATINGS
- ELECTRICAL CHARACTERISTICS
- TIMING OF POWER SUPPLY
- BACKLIGHT CHARACTERISTICS
- EXTERNAL DIMENSIONS
- ELECTRO-OPTICAL CHARACTERISTICS
- INTERFACE DESCRIPTION
- ■REFERENCE APPLICATION CIRCUIT
- REFERENCE INITIAL CODE
- RELIABILITY TEST
- INSPECTION CRITERION
- PACKING SPECIFICATION



#### **GENERAL INFORMATION**

Item	Contents	Unit
LCD type	TFT TRANSMISSIVE	/
Viewing direction	12:00	O' Clock
Module size( $W \times H$ )	41.70 × 56.16	$mm^2$
Viewing area (W×H)	37.40 × 46.16	$mm^2$
Active area (W×H)	34.848 × 43.56	$mm^2$
Number of Dots	176 (RGB) × 220	/
Driver IC	LGDP4524	/
Colors	262K	/
Backlight Type	LED	/
Module Power consumption	220	mw
Interface Type	16-bit CPU bus, 8-bit Compatible	/
Input voltage	2.8/1.8	V

#### ■ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Supply voltage range	IOVcc/Vci/Vcc	-0.3	4.2	V
Input voltage	Vin	-0.3	4.2	V
Operating temperature	Тор	-20	70	°C
Storage temperature	Тѕт	-30	80	°C
Humidity	RH		90%(Max60°C)	RH

#### **■ELECTRICAL CHARACTERISTICS**

#### DC CHARACTERISTICS

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage for logic	Vcc	2.7	2.8	2.9	V
Supply voltage for analog	Vci	2.7	2.8	2.9	V
Supply voltage for I/O	IOVcc	2.7/1.7	2.8/1.8	2.9/1.9	V
Input Current	Idd	-	5.0	10.0	mA
Input voltage ' H ' level	Vih	0.8IOVcc	-	IOVcc	V
Input voltage 'L'level	VIL	-0.3	-	0.2 IOVcc	V
Output voltage ' H ' level	Voh	0.8IOVcc	-	-	V
Output voltage ' L ' level	Vol	-	-	0.2 IOVcc	V



# ■ TIMING OF POWER SUPPLY

PLEASE REFER TO THE DRIVER IC SPECIFICATION.

## ■ BACKLIGHT CHARACTERISTICS

Item	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward voltage	Vf	3.1	3.2	3.3	V	If= 45 mA
Luminance	Lv	3000	3400	3800	cd/m <sup>2</sup>	Ta=25℃
Number of LED	-		3		Piece	-
Connection mode	Р		parallel		-	-

## **Block Diagram**





### EXTERNAL DIMENSIONS





Item		Symbol	Condition	Min	Тур	Max	Unit	Remark	Note
Response	time	Tr+Tf			32	48	ms	FIG 1.	4
Contrast r	ratio	Cr	θ=0°	260	520			FIG 2.	1
Luminance uniformity		δ WHITE	Ø=0° Ta=25℃	80	88		%	FIG 2.	3
Surface Luminance		Lv		200	220		cd/m <sup>2</sup>	FIG 2.	2
			$\emptyset = 90^{\circ}$	58	68		deg	FIG 3.	
Viewing ang	a ranga	0	$\emptyset = 270^{\circ}$	43	53		deg	FIG 3.	6
	e range	Ø	$\emptyset = 0^{\circ}$	59	69		deg	FIG 3.	0
			$\emptyset = 180^{\circ}$	60	70		deg	FIG 3.	
	Red	Х		0.547	0.597	0.647			
	Reu	У		0.286	0.336	0.386			
	Green	Х	A=0°	0.303	0.353	0.403		FIG 2	5
CIE (x, y) chromaticity	Ulteri	у	Ø=0°	0.507	0.557	0.607			
	Blue	Х	£ 0 Ta=25℃	0.096	0.146	0.196		110 2.	
	Dide	у	1a-25 C	0.056	0.106	0.156			
	White	Х		0.239	0.299	0.359			
	vv mite	У		0.249	0.309	0.369			

## **■ELECTRO-OPTICAL CHARACTERISTICS**

Note 1. Contrast Ratio(CR) is defined mathematically as For more information see FIG 2.

Contrast Ratio = <u>Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)</u> Average Surface Luminance with all black pixels (P1, P2, P3, P4, P5)

Note 2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv = Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)

Note 3. The uniformity in surface luminance ,  $\delta$  WHITE is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

δ WHITE =Minimum Surface Luminance with all white pixels (P1, P2, P3, P4, P5)Maximum Surface Luminance with all white pixels (P1, P2, P3, P4, P5)

- Note 4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1. The test equipment is Autronic-Melchers's ConoScope. Series.
- Note 5. CIE (x, y) chromaticity, The x, y value is determined by measuring luminance at each test position 1 through 5, and then make average value.
- Note 6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.
- Note7. For Viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments For contrast ratio, Surface Luminance, Luminance uniformity, CIE The test data is base on TOPCON's BM-5 photo detector.

#### FIG. 1 The definition of Response Time

FORMIKE ELECTRONIC

The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".







Light spot size  $\emptyset$ =7mm, 500mm distance from the LCD surfade to detector lens measurement instrument is TOPCON's luminance meter BM-5







#### ■ INTERFACE DESCRIPTION

Pin	SYMBOL	I/O	Description	Comment
1	GND		Ground	
2	VDD		LCD Power Supply	
3	VDD		LCD Power Supply	
4	CS		Chip select input	
5	RS		Resister select input	
6	WR		Write control input	
7	RD		Read control input	
8	D0	I/O	Data Bus(LSB)	
9	D1	I/O	Data Bus	
10	D2	I/O	Data Bus	
11	D3	I/O	Data Bus	
12	D4	I/O	Data Bus	
13	D5	I/O	Data Bus	
14 15	D6 D7	1/O	Data Bus	
16		1/0	Data Bus	
10	D0	1/0	Data Bus	
18	D3 D10	1/0	Data Bus	
19	D11	1/O	Data Bus	
20	D12	I/O	Data Bus	
21	D13	I/O	Data Bus	
22	D14	I/O	Data Bus	
23	D15	I/O	Data Bus	
24 25	RES IM0		Reset signal input System Interface Mode Select	
26	GND		Ground-	
27	YD		TP	
28	XL		TP	
29	YU			
30				
31	LED-K3			
32				
33	LED-KI			
34	LED-A		LED	

#### ■ APPLICATION CIRCUIT

Please consult our technical department for detail information.

#### ■ INITIAL CODE

Please consult our technical department for detail information.



#### **RELIABILITY TEST**

No.	Test Item	Test Condition	Inspection after test
1	High Temperature Storage	$80\pm2^{\circ}C/200$ hours	
2	Low Temperature Storage	$-30\pm2^{\circ}C/200$ hours	
3	High Temperature Operating	$70\pm2^{\circ}C/120$ hours	
4	Low Temperature Operating	$-20\pm2^{\circ}C/120$ hours	
5	Temperature Cycle	$-20\pm2^{\circ}C\sim25\sim70\pm2^{\circ}C\times10$ cycles (30min.) (5min.) (30min.)	Inspection after $2\sim4$ hours storage at room temperature, the sample shall be free from
6	Damp Proof Test	$50^{\circ}\text{C} \pm 5^{\circ}\text{C} \times 90\%$ RH/120 hours	defects:
7	Vibration Test	Frequency: 10Hz~55Hz~10Hz Amplitude: 1.5mm, X, Y, Z direction for total 3hours (Packing condition)	<ol> <li>Airbubble in the LCD;</li> <li>Sealleak;</li> <li>Non-display;</li> <li>missing segments;</li> <li>Glass crack;</li> </ol>
8	Drooping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	6.Current Idd is twice higher than initial value.
9	ESD test	Voltage: $\pm$ 8KV R: 330 $\Omega$ C: 150pF Air discharge, 10time	

Remark:

1. The test samples should be applied to only one test item.

2.Sample size for each test item is 5~10pcs.

3.For Damp Proof Test, Pure water(Resistance>10M $\Omega$ ) should be used.

4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.

Using ionizer(an antistatic blower) is recommended at working area in order to reduce electro-static voltage.

When removing protection film from LCM panel, peel off the tag slowly( recommended more than one second) while blowing with ionizer toward the peeling face to minimize ESD which may damage electrical circuit.

5.EL evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.

6.Please use automatic switch menu(or roll menu) testing mode when test operating mode.



#### ■ INSPECTION CRITERION

	PAGE 1 OF 4
TITLE: FUNCTIONAL TEST & INSPECTION CRITERIA	MDS Product(B)

This specification is made to be used as the standard acceptance/rejection criteria for Color mobile phone LCM.

1 Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

Major defect: AQL 0.65

Minor defect: AQL 1.5

2. Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within  $45^{\circ}$  against perpendicular line.

3. Definition of inspection zone in LCD.



Zone A: character/Digit area

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.



			PAGE 2	2 OF 4
TITLE:F	UNCTIONAL	TEST & INSPECTION CRITERIA	MDS	Product
4. Inspe 4.1 Ma	ction standa jor Defect	rds		
Item No	Items to be inspected	Inspection Standard	d	Classification of defects
4.1.1	All functional defects	<ol> <li>No display</li> <li>Display abnormally</li> <li>Missing vertical, horizontal segment</li> <li>Short circuit</li> <li>Back-light no lighting, flickering and</li> </ol>	abnormal lighting.	
4.1.2	Missing	Missing component		Major
4.1.3	Outline dimension	Overall outline dimension beyond the dr	awing is not allowed.	

#### 4.2 Cosmetic Defect

Item No	Items to be inspected		Classification of defects				
4.2.1	Clear Spots Black and white Spot defect Pinhole, Foreign Particle, Dirt under polarizer	For dark/white spot, as $\Phi = \frac{(x+y)}{2}$					
		Zone	e Acceptable Qty				
		Size(mm)	A	В	С		Minor
		Ф≤0.10	Igno	ore			
		0.10<Φ≤0.15	2		Ignore		
		0.15<Φ≤0.20	1				
		Φ>0.20	0				
	Dim Spots	2.					
	shaped and dim edged defects	2. Zone	Acc	у			
		Size(mm)	А	В	С		
		$\Phi \leq 0.2$	Ignore				Minor
		$0.20 < \Phi \le 0.40$	3		Ignore		
		$0.40 < \Phi \le 0.60$	2		Ignore		
		$0.60 < \Phi \le 0.80$	1				
		0.80<Φ	0				



							PAGE 3 OF 4				
TITLE: FUNCTIONAL TEST & INSPECTION CRITERIA								MDS Product			
4.2.	Co	smetic Defect					•				
Ite N	em Io	Items to be inspected	Inspection Standard						Classification of defects		
4.2.2		Line defect Black line, White line, Foreign material under polarizer, Polarizer scratch		Size(mm)		Acceptable Qty					
				L(Length)	W(Width)	_	А	B	С		
			-	Ignore	W≤0.02		Igr	lore			
	2.2			L≤3.0	0.02 <w<0.< td=""><td>03</td><td>,</td><td>2</td><td></td><td></td><td rowspan="2">Minor</td></w<0.<>	03	,	2			Minor
				L≤2.0	0.03 <w≤0.< td=""><td>05</td><td></td><td>1</td><td>Ignore</td><td>Ignore</td></w≤0.<>	05		1	Ignore	Ignore	
4.2.3					0.05 <w< td=""><td></td><td>Define dei</td><td>as spot fect</td><td colspan="2"></td><td></td></w<>		Define dei	as spot fect			
			condition or some special angle, jud		Acceptable Qty			ig			
	2.3		L(Length)		W(Width)		A B		С		Minor
				Ignore	W≤0.03		Ignor	e			
			4	5.0 <l≤10.0< td=""><td>0.03<w≤0.< td=""><td>05</td><td colspan="2">2</td><td></td><td></td></w≤0.<></td></l≤10.0<>	0.03 <w≤0.< td=""><td>05</td><td colspan="2">2</td><td></td><td></td></w≤0.<>	05	2				
				L≤5.0	0.05 <w≤0.< td=""><td>08</td><td>1</td><td> 1g</td><td colspan="2">- Ignore</td></w≤0.<>	08	1	1g	- Ignore		
				0.08 <w< td=""><td></td><td>0</td><td></td><td colspan="2"></td><td></td></w<>		0					
4.2.4	Polarize Air bubble	Air bubbles between glass & polarizer									
		2. Zone Size(mm) A			Acceptable Qty						
				A		В	(	С			
		Φ ≤0.2		Igr	Ignore					Minor	
			$0.20 < \Phi \le 0.30$		0	2		Igr	Ignore		
		0.30<Φ≤0.50		0	1						
			$0.50 < \Phi$ 0		0						



				PAGE 4 OF 4		
TITLE:F	roduct					
4.3. Co						
Item No	Items to be inspected	Inspec	Classification of defects			
4.3.5	Glass defect	(i) Chips on corner (i) Chips on corner X $\leq 2.0$ Notes: S=contact pad le Chips on the corner of term into the ITO pad or expose p (ii)Usual surface cracks X $\leq 3.0$ <inner bord<br="">(iii) Crack</inner>	$\frac{Y}{\leq S}$ ength ninal shall not berimeter seal.	$\frac{Z}{\text{Disregard}}$ be allowed to extend $\frac{Z}{\text{eal}}$	Minor	
		Cracks tend to break are crack  1) Not allow IC and FPC	not allowed.	I width is more than	Major	
4.3.6		Not allow chip or solder component is off center more than 50% of the pad outline.       Mino				
4.3.7	SMT	According to the <accept IPC-A-610C class 2 standardefect are Major defect, the or</accept 				



## ■ PACKING SPECIFICATION

# TBD